

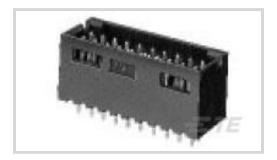
AMPMODU | AMPMODU Headers

TE Internal #: 5-103168-4 PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **12**

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded

Connector & Contact	Terminates To
---------------------	---------------

Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded	
PCB Mount Orientation	Vertical	
Number of Positions	12	
Number of Rows	2	
Board-to-Board Configuration	Parallel	
Electrical Characteristics		
Insulation Resistance	5000 MΩ	
Dielectric Withstanding Voltage (Max)	750 Vrms	
Body Features		
Connector Profile	Standard	
Primary Product Color	Black	
Contact Features		
Mating Square Post Dimension	.64 mm[.025 in]	

PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



PCB Contact Termination Area Plating Material Thickness	2.54 - 5.08 μm[100 - 200 μin]	
Contact Shape & Form	Square	
Contact Underplating Material	Nickel	
PCB Contact Termination Area Plating Material	Tin	
Contact Base Material	Phosphor Bronze	
Contact Mating Area Plating Material	Gold	
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]	
Contact Type	Pin	
Contact Current Rating (Max)	3 A	
Termination Features		
Square Termination Post & Tail Dimension	.64 mm[.025 in]	
Termination Post & Tail Length	3.18 mm[.125 in]	
	Through Hole - Solder	
Termination Method to Printed Circuit Board	Through Hole - Solder	
Termination Method to Printed Circuit Board Mechanical Attachment	Through Hole - Solder	
	Through Hole - Solder With	
Mechanical Attachment		
Mechanical Attachment Mating Retention	With	

Mating Alignment Turne

Polarizatio

Mating Alignment Type	Polarization	
PCB Mount Retention	Without	
PCB Mount Alignment	Without	
Connector Mounting Type	Board Mount	
Housing Features		
Centerline (Pitch)	2.54 mm[.1 in]	
Housing Material	Thermoplastic	
Dimensions		
Row-to-Row Spacing	2.54 mm[.1 in]	
PCB Thickness (Recommended)	1.4 mm[.055 in]	
Usage Conditions		
Housing Temperature Rating	Standard	
Operating Temperature Range	-65 - 105 °C[-85 - 221 °F]	
Operation/Application		
Circuit Application	Signal	

PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



Industry Standards

Compatible With Agency/Standards Products	CSA
Compatible With Approved Standards Products	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	136
Packaging Method	Tray
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC
Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.

Solder Process Capability

Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

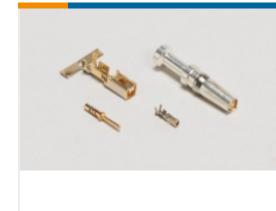






Also in the Series AMPMODU Headers



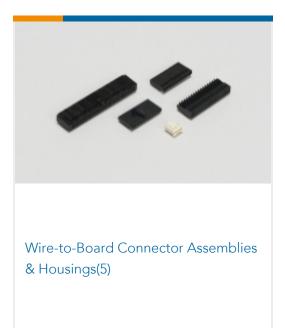






PCB Headers & Receptacles(4349)

Connector Caps & Covers(1)	Connector Contacts(64)	Connector Hardware(2)	PCB Headers & Receptacles(4349)



Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





Documents

Product Drawings 12 MODII HDR DRST SHRD .100CL

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-103168-4_M.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-103168-4_M.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-103168-4_M.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions**of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English